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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Grant Kenji Larsen
Serial No: 09/676,548
Confirmation No: 2719
Filed: September 29, 2000
For: SURFACE STRUCTURE AND METHOD OF MAKING, AND
ELECTROSTATIC WAFER CLAMP INCORPORATING
SURFACE STRUCTURE
Examiner: Stephen W. Jackson
Art Unit: 2836

8/A
T. BELL.
6.26.03

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

The undersigned hereby certifies that this document is being placed in the United States mail with first-class postage attached, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the 10th day of June, 2003.

Cheryl Purcell
Cheryl Purcell

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

RESPONSE UNDER 37 CFR § 1.111

In response to the Office Action mailed January 10, 2003, the following response is submitted in connection with the above-identified application.

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TECHNOLOGY CENTER 2800